



## Product Change Notification - LIAL-28JJJA274

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**Date:**

24 Feb 2020

**Product Category:**

Driver / Interface ICs

**Affected CPNs:****Notification subject:**

CCB 3705 Final Notice: Qualification of GTK as a new assembly site for selected available in 24L SOIC (.300in) package.

**Notification text:****PCN Status:**

Final notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of GTK as a new assembly site for selected available in 24L SOIC (.300in) package.

**Pre Change:**

Assembled at ANAP using 8290 die attach material.

**Post Change:**

Assembled at GTK using EN-4900 die attach material.

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	GREATEK ELETRONIC INC. (GTK)
Wire material	Au	Au
Die attach material	8290	EN-4900
Molding compound material	G600	G600
Lead frame material	A194	A194
MSL	MSL 2	MSL 3

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve on-time delivery performance by qualifying GTK as a new assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

March 24, 2020(date code: 2013)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**



Workweek	February 2019					-->	February 2020					March 2020				
	05	06	07	08	09		05	06	07	08	09	10	11	12	13	14
Initial PCN Issue Date		X														
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date														X		

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**

**February 4, 2019: Issued initial notification.**

**February 24, 2020:** Issued final notification. Update subject to remove the BCDM process technology. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date to be on March 24, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_KSRA-08OFYX715\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

MIC5801YWM

MIC5801YWM-TR

MIC58P01YWM

MIC58P01YWM-TR

MIC59P50YWM

MIC59P50YWM-TR